



Product Change Notification

108251 - 01

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #: 108251 - 01
Change Title: Intel® Flip Chip Ball Grid Array (FCBGA1, FCBGA3, FCBGA5) Chipsets and Advanced Memory Buffer (AMB), PCN 108251-01, Product Material, solder resist material change, Reason for Revision: Change in substrate delivery schedule
Date of Publication: April 10, 2008

Key Characteristics of the Change:

Product Material

Forecasted Key Milestones:

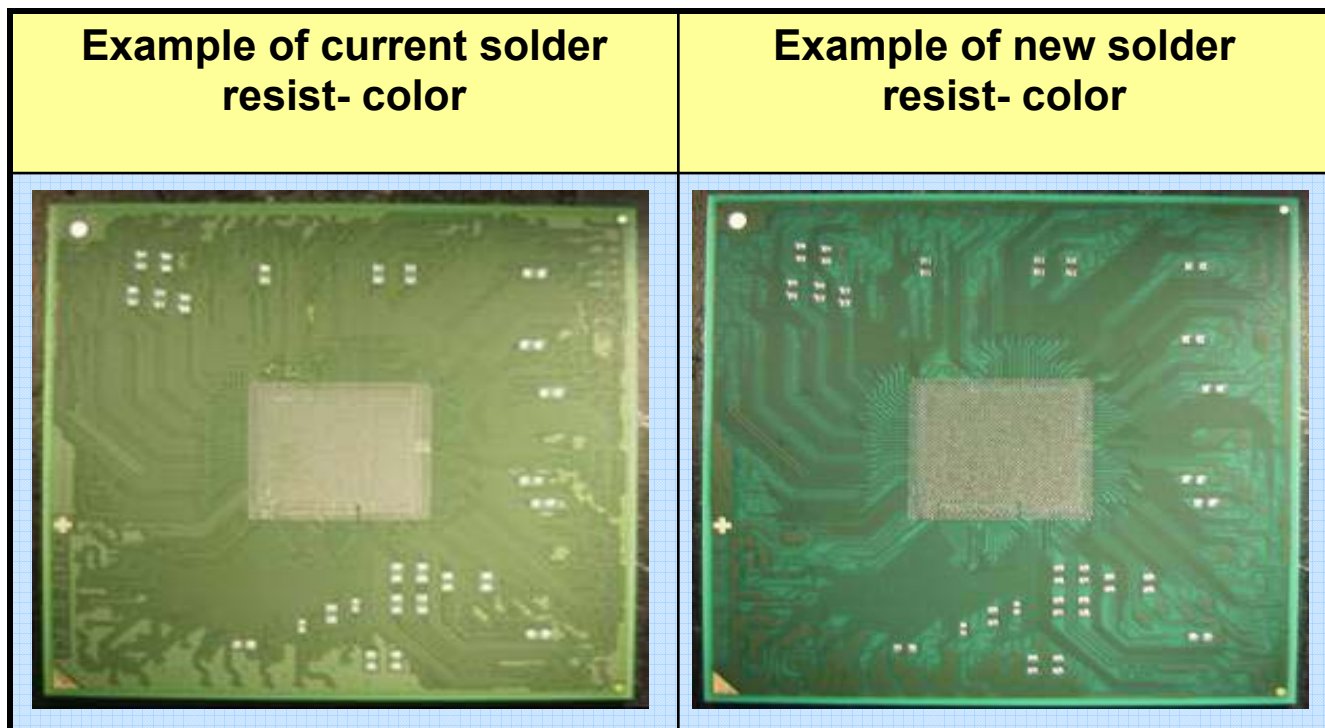
Date Customer Must be Ready to Receive Post-Conversion Material:	May 16, 2008
Date of First Availability of Post-Conversion Material:	May 16, 2008

The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.

Description of Change to the Customer:

Reason for Revision: Change in substrate delivery schedule

The solder resist material has been changed to insure uninterrupted supply of material. There is no change in the functionality of the substrate. There will however be a change in the visual color of the substrate. See photo below.



Customer Impact of Change and Recommended Action:

No anticipated Impact to customer

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	S-Spec	MM#
Intel® 945GMS	QG82945GMS	S L8TC	876223
Intel® 945GM	QG82945GM	S L8Z2	876956
Intel® 945PM	QG82945PM	S L8Z4	876959
Intel® 945GT	QG82945GT	S L8Z6	876960
Intel® 945GME	QG82945GME	S LA9H	890229
Intel® 943GML	QG82943GML	S L9Z9	887279
Intel® 940GML	QG82940GML	S L8Z5	876958
Intel® 945GUXL	QG82945GUXL	S L9T5	885258
Intel® 945GU	QG82945GU	S LA28	887674
Intel® 945G	QG82945G	S L8FU	870299
Intel® 945GZ	QG82945GZ	S L927	877106
Intel® 945GC	QG82945GC	S LA9C	890182
Intel® 3000 MCH	QG3000	S L9Q5	883879
Intel® 3010 MCH	QG3010	S L9Q6	883877
Intel® 945P	QG82945P	S L8HT	870777
Intel® 945PL	QG82945PL	S L8V4	875434
Intel® 945GC	QG82945GC	S L9Z8	887268
Intel® E7230 Memory Controller Hub (MCH)	NQE7230	S L8KK	871522
Intel® E7230 Memory Controller Hub (MCH)	QGE7230	S L8KJ	871520
Intel® 945P	QG82945P	S L8FV	870294
Intel® 975X	QG82975X	S L8YS	876741
Intel® 945PL	QG82945PL	S L93C	877787
Intel® 955X	QG82955X	S L8FW	870291

Marketing Name	Product Code	S-Spec	MM#
Intel® QG6402 Advanced Memory Buffer	QG6402	S L9XC	886483
Intel® QG6402 Advanced Memory Buffer	QG6402	S L9GF	882114
Intel® QG6400 Advanced Memory Buffer	QG6400	S L96G	878953
Intel® 845	RG82845	S L5YQ	838970
Intel® 845E	RG82845E	S L66N	845714
Intel® 845GV	RG82845GV	S L6PU	850149
Intel® 855GM	RG82855GM	S L6WW	852383
Intel® 852GM	RG82852GM	S L6ZK	853196
Intel® 852GME	RG82852GME	S L72K	853564
Intel® 855GME	RG82855GME	S L72L	853565
Intel® 855GME	JG82855GME	S L7VN	864863
Intel® 852GM	JG82852GM	S L7VP	864971
Intel® 852GM	JG82855GM	S L7VL	864974
Intel® 865GV	JG82865GV	S L7YF	865563
Intel® 852GME	JG82852GME	S L8D7	869481
Intel® 845GV	JG82845GV	S L8DA	869483
Intel® 845E	JG82845E	S L8D9	869485
Intel® 845	JG82845	S L8D8	869493
Intel® 915GM	QG82915GM	S L8G6	870323
Intel® 915PM	QG82915PM	S L8G7	870324
Intel® 910GML	QG82910GML	S L8G8	870326
Intel® 915GMS	QG82915GMS	S L8G9	870327
Intel® 865G	JG82865G	S L99Y	879478
Intel® 915GME	QG82915GME	S LA9K	890234
Intel® 910GMLE	QG82910GMLE	S LA9L	890235
Intel® 945GMS	QG82945GMS	S LB2R	897497
Intel® 945GMS	QG82945GMS	S LB2Q	897498

Reference Documents / Attachments:

Document:

Location #:

PCN Revision History:

Date of Revision:

Revision Number:

Reason:

February 15, 2008

00

Originally Published PCN

April 10, 2008

01

Change in substrate delivery
schedule